

Data Sheet January 2000 File Number 3966.2

## 8A, 1200V Hyperfast Dual Diode

The RHRP8120CC is a hyperfast dual diode with soft recovery characteristics ( $t_{rr} < 55$ ns). It has half the recovery time of ultrafast diodes and is of silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as a freewheeling/clamping diode and rectifier in a variety of switching power supplies and other power switching applications. Its low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits, thus reducing power loss in the switching transistors.

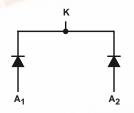
Formerly developmental type TA49096.

## **Ordering Information**

PART NUMBER	PACKAGE	BRAND
RHRP8120CC	TO-220AB	RHR8120C

NOTE: When ordering, use the entire part number.

## Symbol



#### **Features**

	Hyperfast with Soft Recovery<55ns
•	Operating Temperature175°C
•	Reverse Voltage

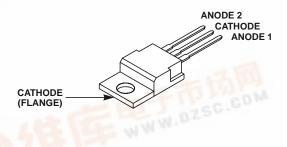
- Avalanche Energy Rated
- · Planar Construction

## **Applications**

- Switching Power Supplies
- Power Switching Circuits
- General Purpose

## **Packaging**

JEDEC TO-220AB



### **Absolute Maximum Ratings** (Per Leg) T<sub>C</sub> = 25°C, Unless Otherwise Specified

	RHRP8120CC	UNITS
Peak Repetitive Reverse VoltageVRRM	1200	V
Working Peak Reverse Voltage	1200	V
DC Blocking VoltageV <sub>R</sub>	1200	V
Average Rectified Forward Current	8	Α
Repetitive Peak Surge CurrentI <sub>FRM</sub> (Square Wave, 20kHz)	16	Α
(Square Wave, 20kHz)  Nonrepetitive Peak Surge Current	100	Α
Maximum Power Dissipation	75	W
Avalanche Energy (See Figures 10 and 11)	20	mJ
Operating and Storage Temperature	-65 to 175	oC



#### RHRP8120CC

**Electrical Specifications** (Per Leg)  $T_C = 25^{\circ}C$ , Unless Otherwise Specified

SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
V <sub>F</sub>	I <sub>F</sub> = 8A	-	-	3.2	V
	$I_F = 8A, T_C = 150^{\circ}C$	-	-	2.6	V
I <sub>R</sub>	V <sub>R</sub> = 1200V	-	-	100	μΑ
	$V_R = 1200V, T_C = 150^{\circ}C$	-	-	500	μΑ
t <sub>rr</sub>	I <sub>F</sub> = 1A, dI <sub>F</sub> /dt = 200A/μs	-	-	55	ns
	$I_F = 8A$ , $dI_F/dt = 200A/\mu s$	-	-	65	ns
t <sub>a</sub>	I <sub>F</sub> = 8A, dI <sub>F</sub> /dt = 200A/μs	-	30	-	ns
t <sub>b</sub>	I <sub>F</sub> = 8A, dI <sub>F</sub> /dt = 200A/μs	-	20	-	ns
Q <sub>RR</sub>	I <sub>F</sub> = 8A, dI <sub>F</sub> /dt = 200A/μs	-	165	-	nC
СЈ	$V_R = 10V, I_F = 0A$	-	25	-	pF
$R_{ heta JC}$		-	-	2	°C/W

#### **DEFINITIONS**

 $V_F$  = Instantaneous forward voltage (pw = 300 $\mu$ s, D = 2%).

I<sub>R</sub> = Instantaneous reverse current.

 $t_{rr}$  = Reverse recovery time (See Figure 9), summation of  $t_a$  +  $t_b$ .

 $t_a$  = Time to reach peak reverse current (See Figure 9).

 $t_b$  = Time from peak  $I_{RM}$  to projected zero crossing of  $I_{RM}$  based on a straight line from peak  $I_{RM}$  through 25% of  $I_{RM}$  (See Figure 9).

 $Q_{RR}$  = Reverse recovery charge.

C<sub>J</sub> = Junction Capacitance.

 $R_{\theta JC}$  = Thermal resistance junction to case.

pw = pulse width.

D = duty cycle.

# **Typical Performance Curves**

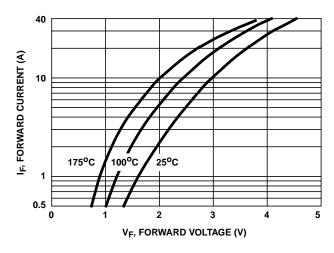


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

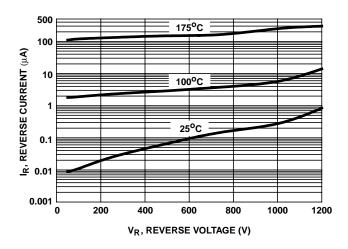


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

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## Typical Performance Curves (Continued)

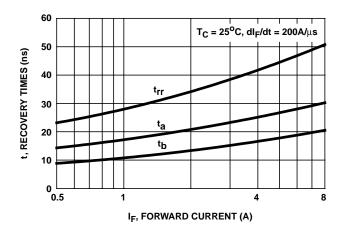


FIGURE 3.  $t_{rr}$ ,  $t_a$  and  $t_b$  curves vs forward current

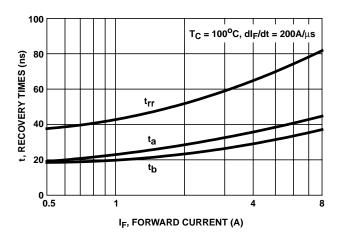


FIGURE 4.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

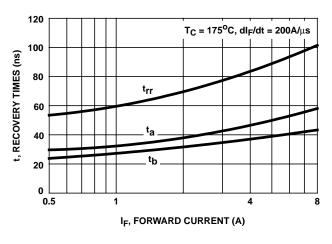


FIGURE 5.  $t_{rr}$ ,  $t_a$  and  $t_b$  curves vs forward current

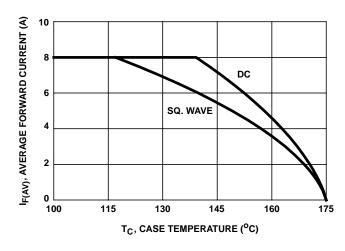


FIGURE 6. CURRENT DERATING CURVE

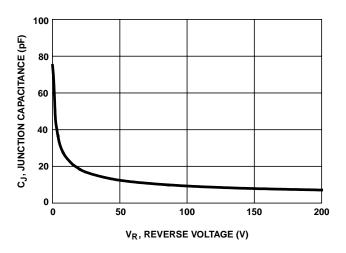


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

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#### RHRP8120CC

#### Test Circuits and Waveforms

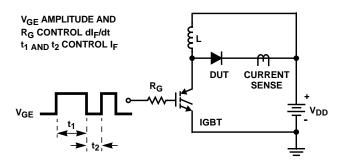


FIGURE 8. t<sub>rr</sub> TEST CIRCUIT

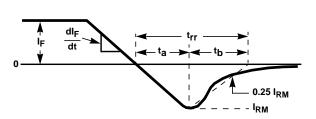


FIGURE 9. t<sub>rr</sub> WAVEFORMS AND DEFINITIONS

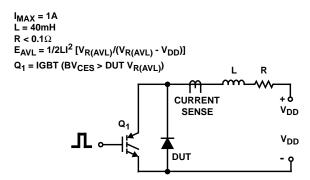


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

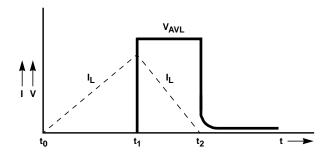


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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